



Material Content Data Sheet



Halogen-Free

Sales Product Name TLD6098-2ES

Issued

09. February 2022

MA# MA005570054

Package PG-TSDSO-24-5

Weight*

111.46 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.848	1.66	1.66	16584	16584
leadframe	inorganic material	phosphorus	7723-14-0	0.016	0.01		139	
	non noble metal	zinc	7440-66-6	0.062	0.06		558	
	non noble metal	iron	7439-89-6	1.243	1.12		11156	
	non noble metal	copper	7440-50-8	50.487	45.28	46.47	452972	464825
wire	non noble metal	copper	7440-50-8	0.455	0.41	0.41	4087	4087
encapsulation	organic material	carbon black	1333-86-4	0.158	0.14		1416	
	plastics	epoxy resin	-	6.154	5.52		55212	
	inorganic material	silicondioxide	60676-86-0	46.285	41.53	47.19	415270	471898
leadfinish	non noble metal	tin	7440-31-5	2.672	2.40	2.40	23972	23972
plating	noble metal	silver	7440-22-4	1.381	1.24	1.24	12387	12387
glue	plastics	epoxy resin	-	0.122	0.11		1093	
	noble metal	silver	7440-22-4	0.575	0.52	0.63	5154	6247
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

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